

#29/D
7/5/02
Hayes

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Applicants:

Date: May 7, 2002

Beaman et al.

Group Art Unit: 2829

Serial No.: 09/382,834

Examiner: V. P. Nguyen

Filed: August 25, 1999

Docket No.: YO993-028BX

For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS,
TEST PROBE AND METHODS OF USE THEREOF

FAX COPY RECEIVED

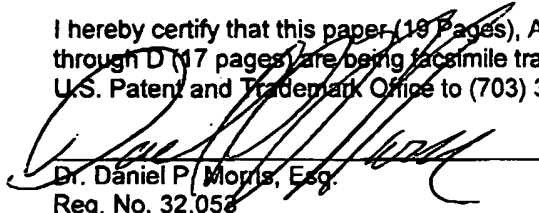
Assistant Commissioner for Patents
Washington, D. C. 20231

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CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (19 Pages), Appendix (10 pages) and Attachments A through D (17 pages) are being facsimile transmitted under Rule 37 CFR 1.61(d) to the U.S. Patent and Trademark Office to (703) 308-7382 on May 7, 2002.


Dr. Daniel P. Morris, Esq.
Reg. No. 32,058WITHDRAWAL OF NOTICE OF APPEAL DATED 3-5-02REQUEST FOR CONTINUED EXAMINATION (RCE)

In response to Office Action dated October 5, 2001, please consider the following:

IN THE CLAIMS

29. (Amended) A method of probing an electronic device by contacting the electronic device with a plurality of flexible contact elements, the method comprising the steps of:

providing a first substrate corresponding to an area of the electronic device to be probed, said substrate having a front surface; [and]

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